Lens Technology Co., Ltd.
藍思科技股份有限公司

(A joint stock company incorporated in the People's Republic of China with limited liability)

(Stock Code: 6613)

INSIDE INFORMATION
ENTERING INTO THE MEMORANDUM OF UNDERSTANDING WITH INTEL CORPORATION

This announcement is made by Lens Technology Co., Ltd. (the "**Company**") pursuant to Rules 13.09(2) and 13.10B of the Rules Governing the Listing of Securities on The Stock Exchange of Hong Kong Limited (the "**Hong Kong Listing Rules**") and the Inside Information Provisions (as defined in the Hong Kong Listing Rules) under Part XIVA of the Securities and Futures Ordinance (Chapter 571 of the Laws of Hong Kong).

OVERVIEW OF THE SIGNING OF THE MEMORANDUM

The board (the "**Board**") of directors (the "**Directors**") of the Company is pleased to announce that, Lens International (HK) Limited ("**Lens International**"), a wholly-owned subsidiary of the Company, recently entered into a memorandum of understanding with Intel Corporation (stock code: NASDAQ: INTC) ("**Intel**") (the "**Memorandum**"). Lens International and Intel are collectively referred to as the "**Parties**".

INFORMATION ON THE COUNTERPARTY

Intel is registered at 2200 Mission College Blvd, Santa Clara, CA 95054. During the three years immediately preceding the date of this announcement, the Company or Lens International have not entered into any other similar memorandum with Intel. Intel possesses leading capabilities in foundational architecture, semiconductor design and global technology standardisation. The Company has had preliminary business contacts with Intel and considers that Intel has the capability to perform its obligations under the Memorandum.

To the best of the Directors' knowledge, information and belief, having made all reasonable enquiries, Intel, as well as its ultimate beneficial owners, are third parties independent of the Company, Lens International and their connected persons.

MAIN CONTENTS OF THE MEMORANDUM

1. Through-Glass Via (TGV) Technology

The Parties intend for TGV advanced packaging to be the primary focus of their discussions under this Memorandum, and Intel considers Lens International to be a valued potential collaborator in this area. The Parties may discuss and evaluate potential collaboration relating to critical processes including, but not limited to, through-hole formation on glass substrates, high-precision laser processing, metal-filled via deposition, and multi-layer interconnect routing. Intel may provide illustrative architecture information, Design for Manufacturing (DFM) guidance, benchmark testing approaches, and validation approaches, in each case subject to separate written agreements. Any engineering validation, qualification, or volume production activity would be defined in, and subject to, a separate written agreement.

2. Additional Opportunities

Beyond TGV, the Parties see meaningful potential to explore other areas where their strengths could come together — for example, structural components and modules for AI PCs, high-reliability structural and thermal components for data center servers, and hardware for embodied AI robotics, industrial intelligent equipment, and edge computing. The Parties will discuss these opportunities as they arise, with any such collaboration to be pursued, if at all, under separate written agreements.

3. Binding and Non-Binding Provisions

Except for the provisions regarding Intellectual Property, Confidentiality and Public Announcements, Dispute Resolution, Limitation of Liability, and Miscellaneous Terms, which are expressly binding, all other provisions do not constitute a commitment to reach a transaction or a specific commercial outcome. This Memorandum shall be effective for a period of one year from the date of signature by the authorised representatives of both Parties, and may be extended upon mutual consultation prior to its expiry.

REASONS FOR AND BENEFITS OF ENTERING INTO THE MEMORANDUM

The Company has long-standing technical accumulation in TGV precision processing, micro-via formation, metallisation deposition and multi-layer interconnection processes. The Company has established relevant pilot lines and commenced sample trial production. At present, the Company has delivered samples to certain potential customers for evaluation, and certain customers have passed preliminary proof-of-concept and entered the technical testing stage.

The Board considers that entering into the Memorandum will help the Company establish a long-term, stable and mutually trusted strategic cooperative relationship with Intel. By leveraging the Parties' respective professional strengths and operational capabilities in areas including precision manufacturing, materials science and global supply chain management, the cooperation is expected to promote the large-scale application of relevant new technologies at an earlier stage and facilitate the realisation of the Company's medium- to long-term strategic objectives.

GENERAL

The Memorandum mainly reflects the preliminary cooperation intentions and arrangements of the Parties at this stage. Save for the provisions relating to intellectual property, confidentiality and public announcements, dispute resolution, limitation of liability and governing law, which are legally binding, the other provisions of the Memorandum do not constitute any commitment to enter into any transaction or achieve any specific commercial outcome. The scope of cooperation, implementation plan, resource commitments, transaction structure and commercial terms under each key area will be separately negotiated by the Parties based on the maturity of the relevant projects, and shall be subject to the formal written agreements subsequently entered into by the Parties. There remains significant uncertainty as to whether and when such subsequent agreements will be entered into.

The TGV advanced packaging business is subject to various uncertainties, including customers' choice of technical routes, the Company's timetable for mass production, progress in technological breakthroughs and market prospects. As at the date of this announcement, the TGV advanced packaging business has not had any substantive impact on the operating results of the Company, and there remains significant uncertainty as to whether, and when, the Company will be able to realise the expected benefits in this area.

The cooperation contemplated under the Memorandum, if materialised, may constitute a notifiable transaction of the Company under Chapter 14 of the Hong Kong Listing Rules. If the Parties enter into any definitive agreement(s), or if there are any material developments in respect of the cooperation contemplated under the Memorandum, the Company will make further announcement(s) in accordance with the applicable laws and regulations, including but not limited to the Rules Governing the Listing of Securities on the Shenzhen Stock Exchange and the Hong Kong Listing Rules.

Shareholders of the Company and/or investors should note that the Memorandum may or may not lead to the entering into of any definitive agreement(s), and the whole or any part of the cooperation may or may not be implemented or materialised. Shareholders of the Company and/or investors are reminded to exercise caution when dealing in the securities of the Company.

By order of the Board
Lens Technology Co., Ltd.
Chau Kwan Fei
Chairman of the Board

Hong Kong, July 24, 2026

As of the date of this announcement, the Board comprises: (i) Ms. Chau Kwan Fei, Mr. Cheng Chun Lung and Mr. Rao Qiaobing as executive Directors; and (ii) Ms. Wan Wei, Mr. Liu Yue, Mr. Tian Hong and Mr. Tang Xiangxi as independent non-executive Directors.